

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: **CHII-MING WU, MING-HSING TSAI, CHING-HUA HSIEH, SHAU-LIN SHUE**

For: **METHOD OF MANUFACTURING A CONTACT INTERCONNECTION LAYER CONTAINING A METAL AND
NITROGEN BY ATOMIC LAYER DEPOSITION FOR DEEP SUB-MICRON SEMICONDUCTOR TECHNOLOGY**

Enclosed are:

- 6** sheets of drawing(s) - formal.
- An assignment of the invention to **Taiwan Semiconductor Manufacturing Co.**
- An associate power of attorney Applicant claims small entity status
- Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY
FOR:	NO. FILED	NO. EXTRA
BASIC FEE		
TOTAL CLAIMS	51 -20=	31
INDEP CLAIMS	5 -3=	2
		x 18 =
		x 84 =
		SUB TOTAL
		\$ 1,476.
		ASSIGNMENT
		\$40.
		TOTAL
		\$ 1,516.

- Please charge my Deposit Account No. 19-0033 in the amount of **\$ 1,516**. A duplicate copy of this sheet is enclosed.
- The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
- Any additional filing fees required under 37 CFR §1.16.
- Any patent application processing fees under 37 CFR §1.17.

Respectfully submitted
George J. Saile
GEORGE J. SAILE, REG. NO. 19,572

EXPRESS MAIL CERTIFICATE

Express Mail No. EV313927030US

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

9/8/03
Date of deposit

George J. Saile 9/8/03
Signature / Date

22387 U.S.P.T.O.
10/6/03
09/08/03